September 25, 2019

Business Segment: ELECTRONICS

MACDERMID ALPHA TO PRESENT AT IMAPS INTERNATIONAL SYMPOSIUM ON MICROELECTRONICS

(Waterbury, CT USA) – September 25, 2019 MacDermid Alpha Electronics Solutions, leaders in the production of specialty chemistries and electronic soldering and bonding materials, will be presenting during the IMAPS International Symposium on Microelectronics at the Hynes Memorial Convention Center in Boston, Massachusetts, USA held September 30 – October 3, 2019.

Shaopeng Sun, R&D Chemist, will present “Nickel Via Fill Metallization” on Tuesday, October 1st at 5:15pm, Session 029. In his paper, Mr. Sun will explore the possibility of nickel via fill metallization by electrodeposition achieving similar bottom-up fill as copper chemistry. “It becomes critical for semiconductor manufacturers to find ways to improve interconnect reliability while reducing cost” said Shaopeng. “If nickel does not represent a significant penalty in the replacement of copper then the potential benefits of simplicity, cost reduction, and increased reliability would weigh in its favor.”

Our Semiconductor Solutions Division is a global leader in high performance semiconductor chemistries and assembly materials that engages directly with OEMs, IDMs, wafer foundries, OSATs and tool suppliers to collaboratively develop solutions that meet the fast-paced semiconductor market demands.

For the times and locations for these papers and general information on the symposium, please visit IMAPS 2019 program at http://www.imaps.org/imaps2019/program.htm

For more information on Mr. Sun’s paper, contact him at Shaopeng.Sun@MacDermidAlpha.com